

Amendment to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application.

List of Claims:

1. (Currently Amended): A semiconductor device having a multilayer wiring structure, comprising:
 - a semiconductor substrate;
 - a lower dielectric layer arranged on the substrate and having an opening, a lower conductive portion filling the opening, and at least one dielectric member embedded in the lower conductive portion;
 - an interlayer dielectric film arranged on the lower dielectric layer and having a contact wiring; and
 - an upper dielectric layer arranged on the interlayer dielectric film and having an upper opening, an upper conductive portion filling the upper opening, and at least one dielectric member embedded in the upper conductive portion, wherein the upper conductive portion ~~dielectric layer~~ and the lower conductive portion ~~dielectric layer~~ are electrically connected by the contact wiring.

Claim 2 (Original): The semiconductor device according to claim 1, wherein at least one dielectric member is arranged in an island-like manner in the opening.

Claim 3 (Canceled).

Claim 4 (Previously Presented): The semiconductor device according to claim 1, wherein the upper conductive portion includes an external electrode terminal.

Claim 5 (canceled).

Claim 6 (Currently Amended): A semiconductor device having a multilayer wiring structure, comprising:

a semiconductor substrate;

a lower dielectric layer arranged on and in direct contact with the substrate and including an upper surface, a lower surface, an opening, at least one first dielectric member arranged in the opening, and a lower conductive portion filling the opening so as to surround the at least one first dielectric member;

an interlayer dielectric film arranged on the lower dielectric layer and having a contact wiring; and

an upper dielectric layer arranged on the interlayer dielectric film and having an upper opening, at least one second dielectric member arranged in the upper opening, and an upper conductive portion filling the upper opening so as to surround the at least one second dielectric member, wherein the upper conductive portion and the lower conductive portion are electrically connected by the contact wiring.

Claim 7 (Currently Amended): The semiconductor device according to claim 6, wherein the at least one first dielectric member has a height that is the same as the thickness of the lower dielectric layer.

Claim 8 (Currently Amended): The semiconductor device according to claim 6, wherein the at least one first dielectric member has an end flush with the upper surface of the lower dielectric layer ~~film~~ and a further end flush with the lower surface of the lower dielectric layer .

Claim 9 (Previously Presented): The semiconductor device according to claim 6, wherein the at least one first dielectric member is one of a plurality of separated dielectric members.

Claim 10 (Currently Amended): The semiconductor device according to claim 6, wherein the lower conductive portion has a flat surface flush with the upper surface of the lower dielectric layer.

Claim 11 (Canceled).

Claim 12 (Previously Presented): A semiconductor device comprising:

a semiconductor substrate;

a lower dielectric layer arranged on and in direct contact with the semiconductor substrate and having a lower pad, wherein the lower pad includes a lower through hole, a lower conductive metal filling the lower through hole, and at least one dielectric member enclosed by the conductive metal;

an interlayer dielectric film arranged on the lower dielectric layer and having a contact wiring; and

an upper dielectric layer arranged on the interlayer dielectric film having an upper pad, wherein the upper pad includes an upper through hole, an upper conductive metal filling the upper through hole, and at least one second dielectric member enclosed by the upper conductive metal, and wherein the upper conductive metal is electrically connected to the lower conductive metal via the contact wiring of the interlayer dielectric film.

Claim 13 (Previously Presented): The semiconductor device according to claim 12, wherein the lower conductive portion and the upper conductive portion are arranged vertically.

Claim 14 (Previously Presented): The semiconductor device according to claim 13, wherein the contact wiring of the interlayer dielectric film includes a through hole, a conductive metal filling the through hole, and at least one dielectric member enclosed by the conductive metal.